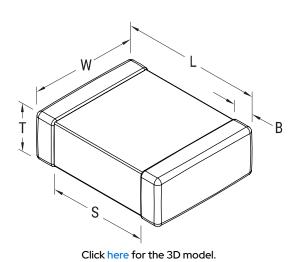


**General Information** 

Series



SMD Comm X8G HT150C, Ceramic, 0.12 uF, 5%, 50 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



	Style	SMD Chip
	Description	SMD, MLCC, High Temperature, Ultra-Stable
	Features	High Temperature, Ultra-Stable
	RoHS	Yes
	Termination	Tin
	Marking	No
	AEC-Q200	No
	Typical Component Weight	130 mg
	Shelf Life	78 Weeks
	MSL	1

SMD Comm X8G HT150C

Dimensions			
2220			
5.7mm +/-0.4mm			
5mm +/-0.4mm			
1mm +/-0.15mm			
3.5mm MIN			
0.6mm +/-0.35mm			

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	4000

Specifications			
Capacitance	0.12 uF		
Measurement Condition	1 kHz 1.0Vrms		
Tolerance	5%		
Voltage DC	50 VDC		
Dielectric Withstanding Voltage	125 VDC		
Temperature Range	-55/+150°C		
Temp. Coefficient	X8G		
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms		
Dissipation Factor	0.1% 1 kHz 1.0Vrms		
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours		
Insulation Resistance	8.3333 GOhms		

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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